



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-03-16
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	8B72*UAM3AA5	A	ZW1A	2013-07-04
Amount	UoM	Unit type	ST ECOPACK Grade	
29.800	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	3X3X1	20	No lead	
Comment	Package: VFQFPN 16 3x3x1.0 PITCH 0.50, MD valid for CP:PM8903ATR.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	8872*UAM3AA5					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
SILICON DIE	Other inorganic materials	1.306	mg	supplier	DIE	Silicon (Si)	7440-21-3		1.226	mg	938744	41141
SILICON DIE				supplier	BACK SIDE METALLIZATION	Chromium (Cr)	7440-47-3		0.003	mg	2297	101
SILICON DIE				supplier	BACK SIDE METALLIZATION	Gold (Au)	7440-57-5		0.006	mg	4594	201
SILICON DIE				supplier	BACK SIDE METALLIZATION	Nickel (Ni)	7440-02-0		0.012	mg	9188	403
SILICON DIE				supplier	BACK SIDE METALLIZATION	Vanadium (V)	7440-62-2		0.003	mg	2297	101
LEADFRAME	Copper and its alloy	17.173	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		14.249	mg	829733	478154
LEADFRAME				supplier	ALLOY	Iron (Fe)	7439-89-6		0.351	mg	20439	11779
LEADFRAME				supplier	ALLOY	Zinc (Zn)	7440-66-6		0.02	mg	1165	671
LEADFRAME				supplier	ALLOY	Iron Phosphide(FeP)	26508-33-8		0.006	mg	349	201
LEADFRAME				supplier	COATING	Nickel (Ni)	7440-02-0		2.481	mg	144471	83255
LEADFRAME				supplier	COATING	Palladium (Pd)	7440-05-3		0.053	mg	3086	1779
LEADFRAME				supplier	COATING	Gold (Au)	7440-57-5		0.013	mg	757	436
DIE ATTACH	Other organic materials	0.477	mg	supplier	GLUE	Acrylates	Proprietary		0.062	mg	129979	2081
DIE ATTACH				supplier	GLUE	Silver (Ag)	7440-22-4		0.382	mg	800839	12819
DIE ATTACH				supplier	GLUE	Dicyclopentenyloxyethyl methacrylate	68586-19-6		0.014	mg	29350	470
DIE ATTACH				supplier	GLUE	2-propionic acid methylester reaction product	Proprietary		0.014	mg	29350	470
DIE ATTACH				supplier	GLUE	Bis(α,α-dimethylbenzyl) peroxide	80-43-3		0.005	mg	10482	168
BONDING WIRE	Other inorganic materials	0.796	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		0.796	mg	1000000	26711
ENCAPSULATION	Other organic materials	10.048	mg	supplier	MOLDING COMPOUND	Epoxy resin	25068-38-6		0.502	mg	49960	16846
ENCAPSULATION				supplier	MOLDING COMPOUND	Silica fused (SiO2)	60676-86-0		8.943	mg	890028	300101
ENCAPSULATION				supplier	MOLDING COMPOUND	Phenol Resin	29690-82-2		0.301	mg	29956	10101
ENCAPSULATION				supplier	MOLDING COMPOUND	Zinc hydroxide	20427-58-1		0.282	mg	28065	9463
ENCAPSULATION				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		0.02	mg	1990	671